

What is claimed:

1. A composition effective for dissolving a cured polymeric resin comprising:

- (a) an organo-fluorine component of the formula  $“(CH_3CH_2CH_2CH_2)_4NF-(H_2O)_3”$ ;
  - (b) a soluble amine component of the formula  $“C_9H_{16}N_2$  or  $(C_2H_5)_2NOH”$ ;
  - (c) a solvent for components a and b; and
  - (d) wherein the proportion of “a” and “b” is between about 0.1 wt% and about 15 wt%.
2. The composition of claim 1 which includes a compatible surfactant.
  3. The composition of claim 1 wherein “b” is 1,8-diazabicyclo(5.4.0)undec-7-ene (DBU).
  4. The composition of claim 3 wherein “a” is tetrabutylammonium fluoride.
  5. The composition of claim 1 wherein the solvent “c” is selected from methyl ethyl ketone and n,n-dimethylacetamide.
  6. The composition of claim 2 wherein “b” is selected from 1,8-diazabicyclo(5.4.0)undec-7-ene (DBU) and diethylhydroxylamine.
  7. The composition of claim 1 wherein “b” is 1,8-diazabicyclo(5.4.0)undec-7-ene (DBU) and “c” is selected from n,n-dimethylacetamide and methyl ethyl ketone.
  8. The composition of claim 2 wherein “b” is selected from 1,8-diazabicyclo(5.4.0)undec-7-ene (DBU) and diethylhydroxylamine and “c” is selected from n,n-dimethylacetamide and methyl ethyl ketone.
  9. A process for removing cured polymeric resin from the surface of substrates containing a layer of cured resin comprising coating said cured resin layer with the composition of claims 1, allowing sufficient lapse of

time to permit the dissolution of the resin and flushing the dissolved resin from the substrate with a rinse.

10. A process for removing cured polymeric resin from the surface of substrates containing a layer of cured resin comprising coating said cured resin layer with the composition of claim 2, allowing sufficient lapse of time to permit the dissolution of the resin and flushing the dissolved resin from the substrate with a rinse.
11. A process removing cured polymeric resin from the surface of substrates containing a layer of cured resin comprising coating and said cured resin layer with a composition of claims 6, allowing sufficient lapse of time to permit the dissolution of the resin and flushing the dissolved resin from the substrate with a rinse.
12. The process of claim 9 wherein the cured resin to be removed from the substrate is a cured silicone.